Special Issue

Advances in Wearable Sensors

Message from the Guest Editor

Recently, advances in wearable sensors have actuated the evolution of not only personalized healthcare but also IoT applications. The barriers to practical application and usage of wearable sensors began being leveraged by the developments of deformable materials and technologies, especially manufacturing at the micro and nano-scales. However, unlike solid-state sensors, most deformable sensors, particularly stretchable ones, are yet incorporable to a broad range of advances in microelectromechanical (MEMS) that are crucial to unleash their full potential for advanced sensing devices and systems. Accordingly, this Special Issue welcomes all researchers to share breakthrough ideas and studies – including original papers and review articles – on the developments of wearable materials and technologies, including process optimization, quality assurance approaches and metrology.

- wearable sensors and technologies
- deformable materials processing
- experimental and theoretical optimizations
- MEMS-based fabrication and integration
- IoT sensing applications

Guest Editor

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Deadline for manuscript submissions

closed (15 August 2021)

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/si/59181

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